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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Application Number	10/538306
				Confirmation Number	Not yet assigned
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				First Named Inventor	Makoto UEKI
				Art Unit	Not yet assigned
				Examiner Name	Not yet assigned
Sheet	1	of	1	Attorney Docket Number	Q88465

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ³ (if known)		
		US			
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FOREIGN PATENT DOCUMENTS							
Examiner Initials*	Cite No. ¹	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation ⁶
		Country Code ³	Number ⁴	Kind Code ⁵ (if known)			
AA		JP	2000-150522	A	05-30-2000		
AA		JP	2001-298084	A	10-26-2001		
AA		JP	2000-208517	A	07-28-2000		
AA		JP	11-102909	A	04-13-1999		
AA		EP	0751567	A2	01-02-1997		
AA		JP	09-064033	A	03-07-1997		
AA		JP	02-165632	A	06-26-1990		

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation ⁶
AA		E.T. Ogawa et al., "Stress-Induced Voiding Under Vias Connected To Wide Cu Metal Leads", Proceedings of IEEE International Reliability Physics Symposium 2002, USA, The Electron Device Society and The Reliability Society of the Institute of Electrical and Electronics Engineers, Inc, April 7, 2002, Pages 312-321	

Examiner Signature	/Ajay Arora/	Date Considered	10/16/2006
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